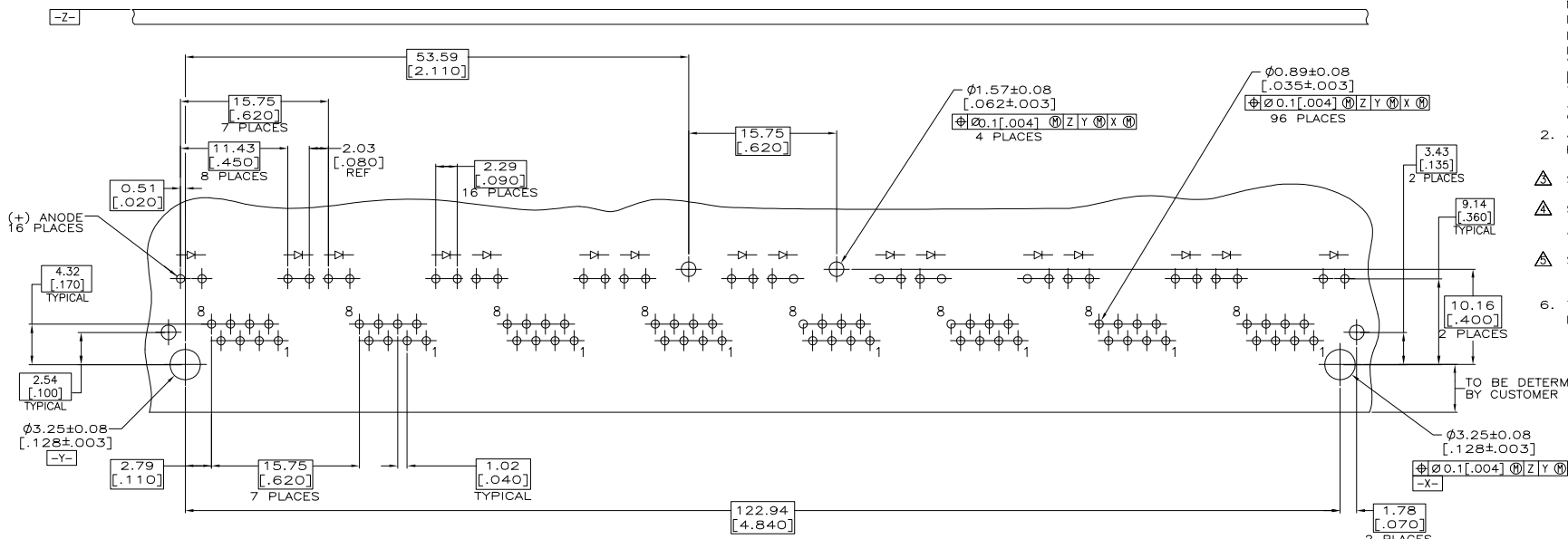
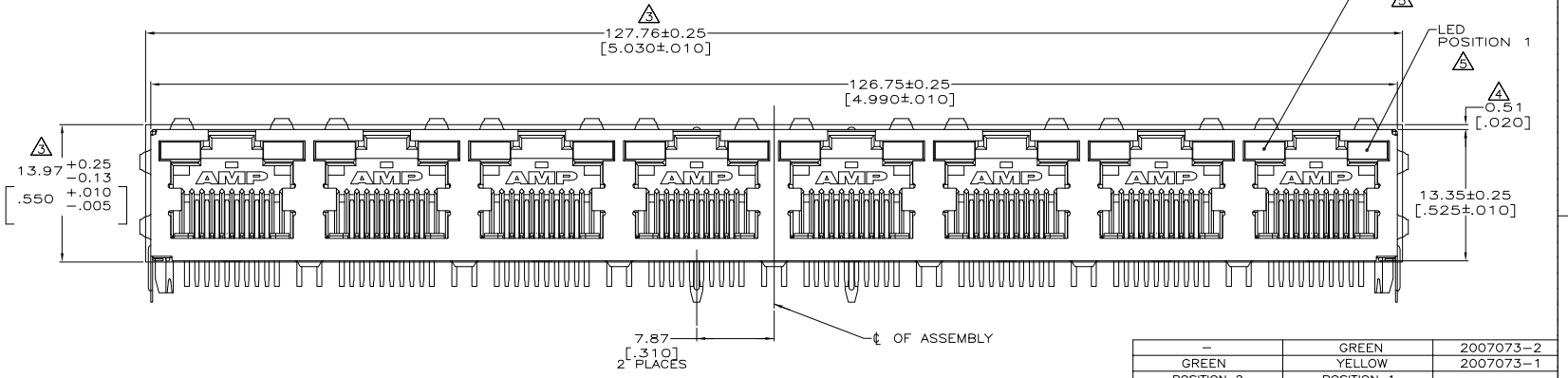
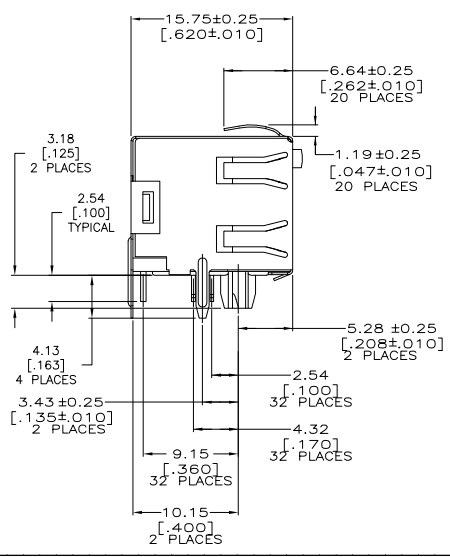


| LOC | DIST | REVISONS | |
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| AA | 00 | | |
| REV | DATE | BY | APP |
| B1 | 22APR2009 | TY | SY |



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE. CONTACT LUBE ON GOLD PLATED PORTION
SHIELD - 0.196[.0077] THICK COPPER ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm [.0003500] THICK Sn/Cu OVER 2.03µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu 3.56µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
 - △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 - △ SEE TABLE FOR COLOR OF LEDS.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



| | | |
|----------------------------------|------------|-------------|
| | GREEN | 2007073-2 |
| | YELLOW | 2007073-1 |
| POSITION 2 | POSITION 1 | PART NUMBER |
| INDICATOR COLOR FOR EACH HOUSING | | |

| | | | | | |
|--|--|-----------------|-------------------------|--------------------|------------------------------------|
| THIS DRAWING IS A CONTROLLED DOCUMENT. | | DATE: 16APR2007 | BY: B. LATTUCA/LA.MAYER | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| DIMENSIONS: mm (INCHES) | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| DRAWN BY: J. WESTMAN | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| PRODUCT SPEC: 108-1163-4 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| APPLICATION SPEC: 114-2154 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| MATERIAL: SEE NOTE 1 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| WEIGHT: SEE NOTE 1 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| CUSTOMER DRAWING | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| SCALE: 4:1 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| SHEET: 1 of 1 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |
| REV: B1 | | DATE: 16APR2007 | BY: J. WESTMAN | APP: B. BLICKINGER | NAME: Teco Electronics Corporation |